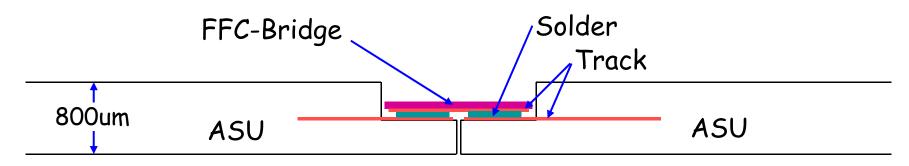


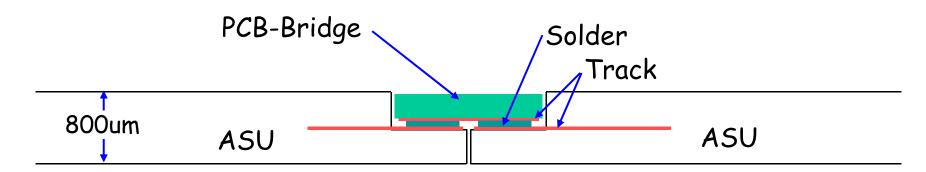
- Flexi and Rigid Bridges shown to be viable:
 - . Compatible with 0.8mm (and thicker) ASU
 - > 120 connections across ASU
 - Halogen lamp soldering system
 - $2-3m\Omega$ per bond
 - Good signal propagation
 - Lead-free, leaded, and Sn/Bi options (220°, 183°, 150° C)
 - Re-work possible
 - . Cheap



Short FFC (Flat,Flexible-Cable) Bridges make connections on a 1mm pitch – OK for at least 120 connections



Alternatively the Bridges can be thin PCBs, also with 1mm pitch connections. This gives a mechanical as well as electrical joint



Maurice Goodrick & Bart Hommels , University of Cambridge

ECAL DIF - Kinked Flexi Bridges

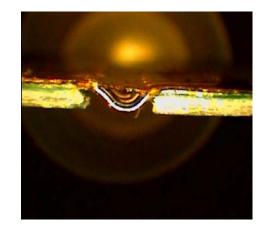


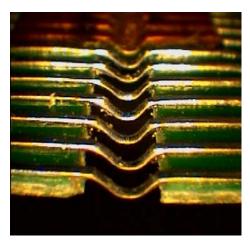
Pre-formed kink for increased flexibility

- . Up-kink and Down-kink options
- Needs ~1mm gap between ASUs (is this a problem?)



DOWN Kink





Kapton in placeKapton removedMaurice Goodrick & Bart Hommels , University of Cambridge



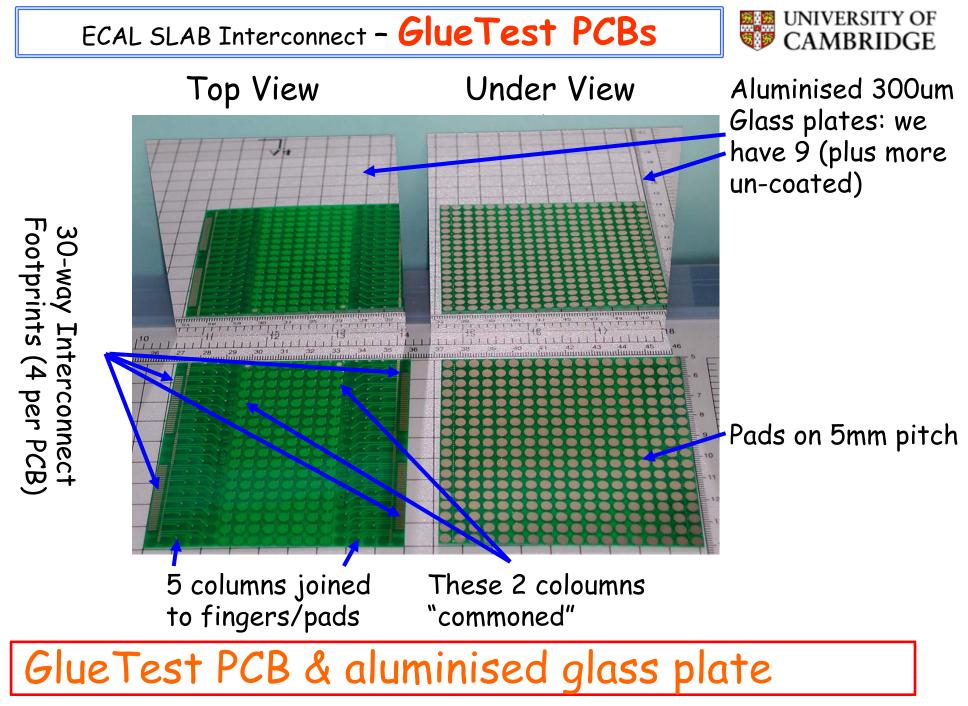
• Halogen heat source :

- Good heating profiles have been established using:
 - . 140mm filament with elliptical reflector
 - Variac power control, Manual timing
 - Video observation and Temperature recording
- Easy to make on-line, USB based computer control?
- Should be possible to scale for full production



• Effect on Detector Glue Connections

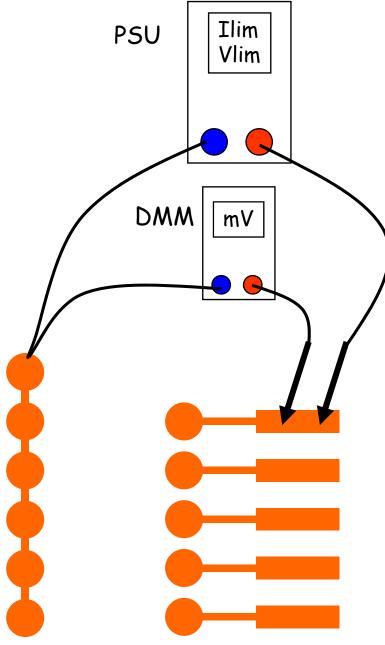
- . Does soldering cause joint deterioration?
- . If not, what about rework?
- Preliminary findings
- Before soldering:
 - Need ~4v to form connection (oxide breakdown?)
 - Even then, fraction of an Ohm connection
- After soldering (Sn/Bi solder):
 - Re-forming required
 - Similar formed joint resistance
- Does this matter for a real detector?
 - . Plenty of Volts, but low current



Maurice Goodrick & Bart Hommels , University of Cambridge

ECAL SLAB Interconnect - GlueTest Initial





GlueTest - PCB #1

Connector #1									
I Lim(mA)	50	50	50	50	50	100			
V Lim (V)	1	2	3	4	1	1			
Finger									
0	9.2	9.2	9.2	9.2	9.1	18			
1	9	9	9	9	9	18			
2	9.6	9.6	9.6	9.6	9.6	19			
3	9.1	9	9	9.1	9	18			
4	1000	2000	3000	22	21	43			
5	1000	114	66	18	17	35			
6	1000	2000	3000	20	20	40			
7	1000	2000	3000	23	23	46			
8	1000	2000	3000	28	27	56			
9	1000	160	18	19	19	38			
10	1000	87	18	18	18	37			
11	1000	2000	22	24	24	49			
12	470	31	15	15	14	30			
13	180	31	17	17	16	33			
14	1000	2000	33	29	29	58			
15	1000	2000	3000	22	22	44			
16	1000	31	16	16	16	32			
17	1000	2000	3000	18	19	38			
18	120	27	28	16	16	33			
19	1000	38	18	18	18	36			
20	1000	2000	3000	18	18	36			
21	1000	2000	3000	20	20	41			
22	1000	2000	3000	18	17	35			
23	1000	2000	15	15	15	30			
24	1000	2000	19	19	19	39			
25	215	124	49	40	39	78			
26	1000	2000	23	16	16	33			
27	1000	2000	34	24	24	49			
28	1000	2000	20	21	21	42			
29	12	12	12	12	12	24			



• Effect on Detector characteristics

- Does soldering or re-work degrade detector?
- Working on Czech 6x6 cm detectors with 10mm pads
- Already characterised at LAL
- We are building probe card to repeat bare detector characterisation (I-V and C-V)
- . Then detector will be glued to GlueTest PCB (4 pads to 1) at Manchester
- Then same card will be used to check characteristics
- Solder interconnect to neighbour
- Re-check characteristics



Laser Soldering:

- Precise heat delivery
- Promises lower heating of glue joint
- . Initial tests at Hull have made joints through the Kapton of the Flexi Bridge
- Possibly going to be a bit slow





James Gilbert University of Hull Hull, UK



Laser Soldering: plans

- Not expensive to purchase 40W semiconductor laser
- Would need X-Y table and interlocked enclosure
- Control software required
- . This is a not inconsiderable package of work
- We would like to await the detector-damage results, and for the UK funding to clarify



Backup slides follow



Update on Investigations at Cambridge

- . Recap
- . Lines of Enquiry
- . Bits and Boards
- . Where we are



We have been looking at using "Bridges" to jumper multiple connections between adjacent ASUs

The Bridge would be soldered onto pads on the ASU (or DIF) PCB

Each Bridge would provide >=30 connections Up to 4 Bridges fit in the width of an ASU ... 1 per path would be an ideal solution ©©



Provides copious connections (4 x 30 across ASU)

- plenty for Power Planes
- . would allow 4 or more rows of connections
- Solder joints well proven electrically
- Signal transmission likely to be less compromised
 Rework possible

 Using an FFC-Bridge would make the mechanical joint independent: this might appeal to the mechanical designers

 Using a PCB-Bridge combines mechanical and electrical joint

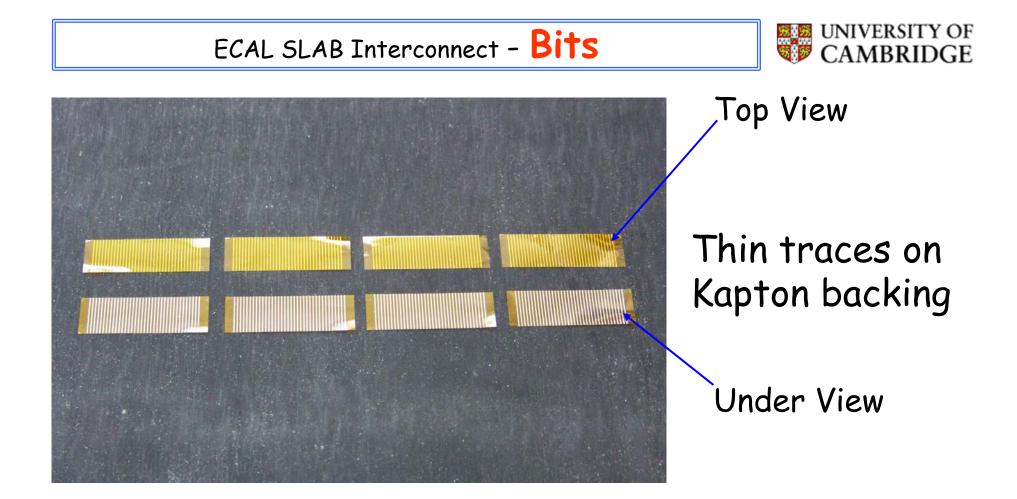


. How to solder the joints

- . IR using linear Quartz-Halogen lamp
- Laser Soldering
- Signal Integrity
 - . Signal delivery along LVDS lines
 - . Crosstalk

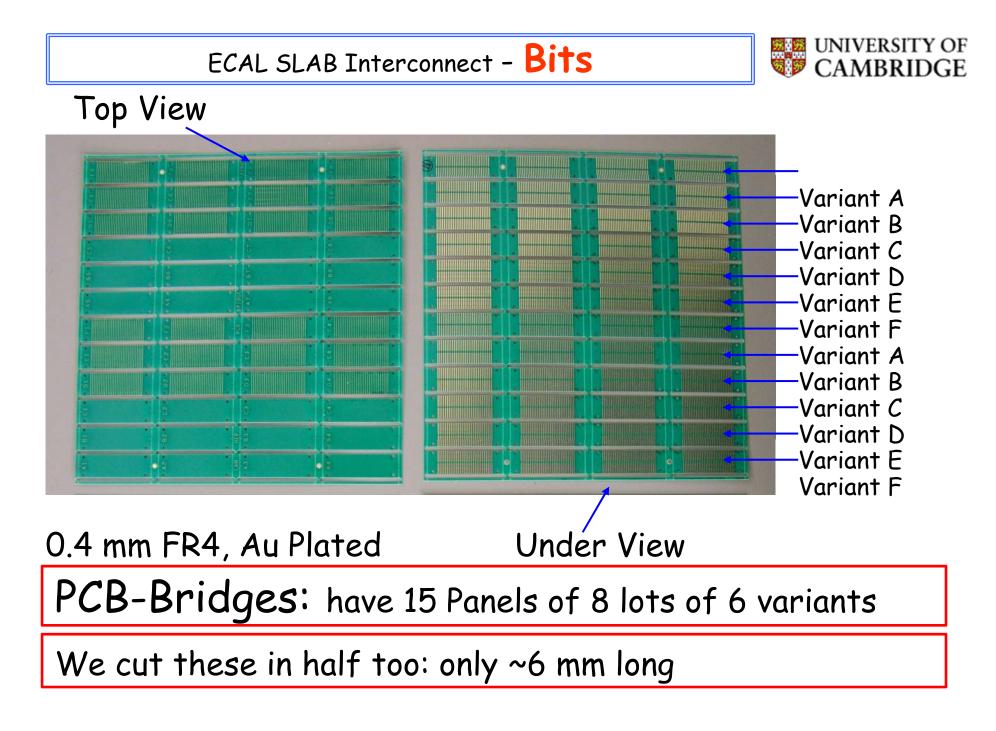
. Effect on Detector Glue Connections

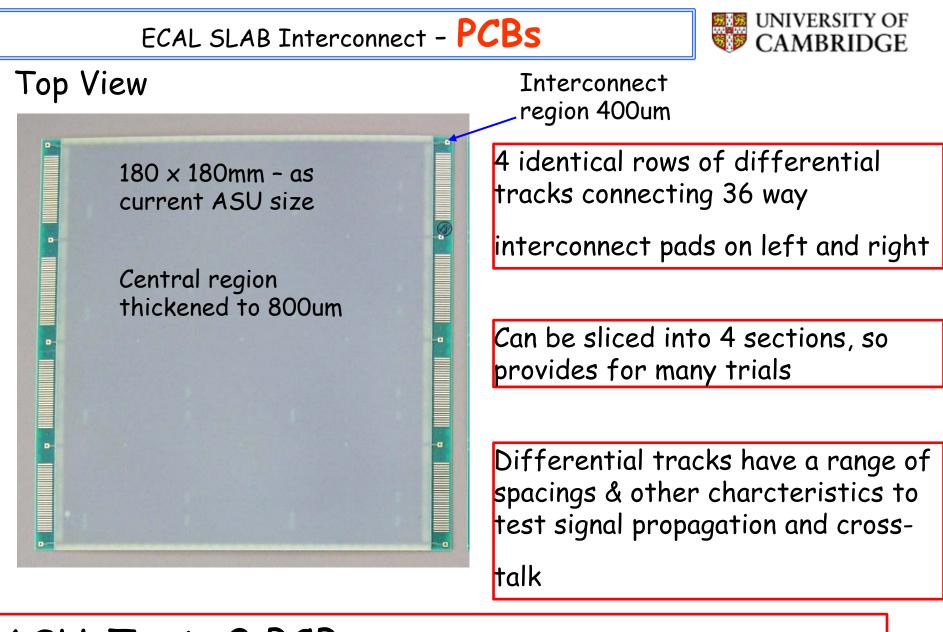
- Does soldering cause joint deterioration?
- . If not, what about rework?



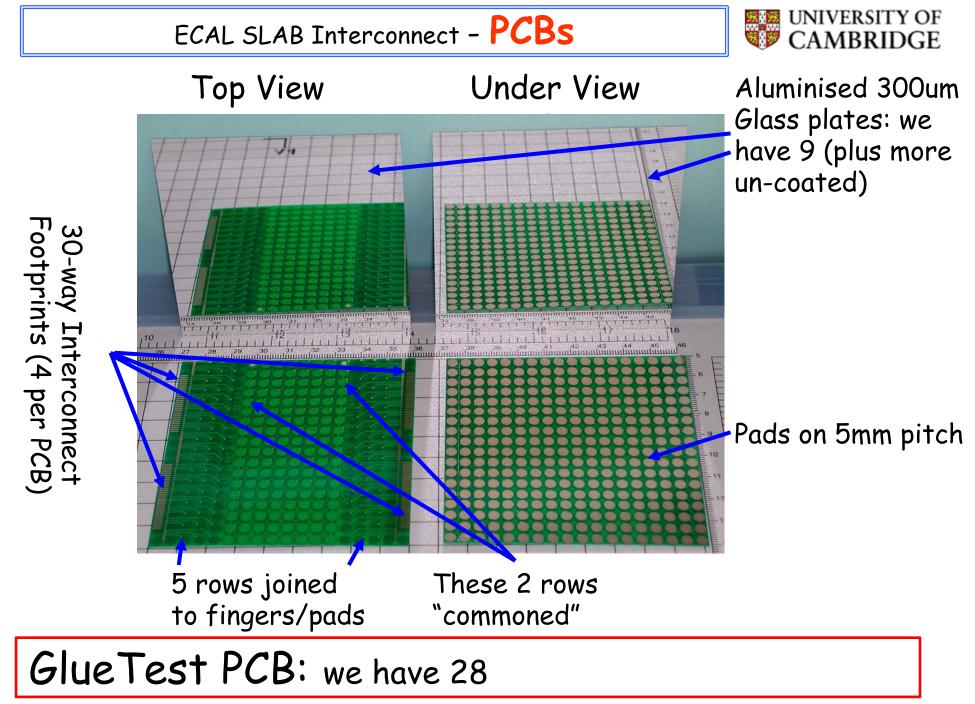
FFC-Bridges: we have 250 cut, 250 on roll

We now cut them in half: only ~6 mm long



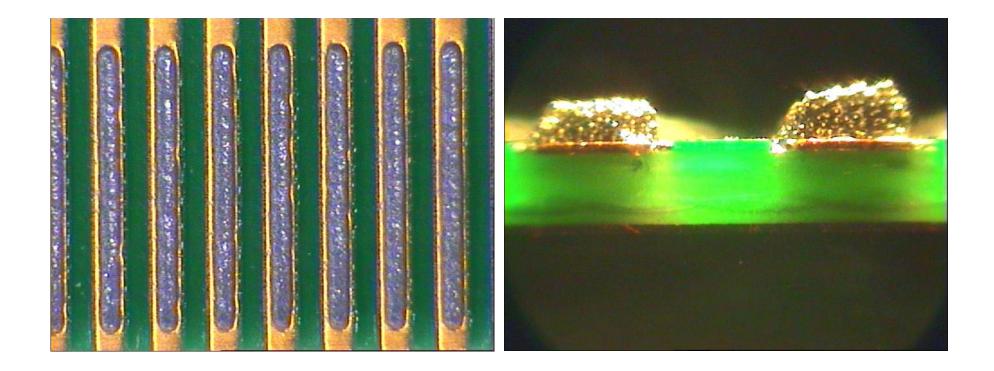


ASU-Test_2 PCB: we have 15



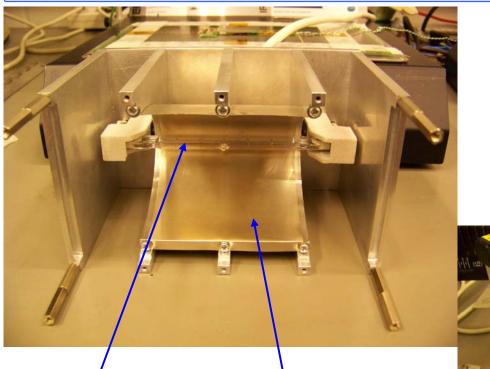
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PCB-Bridges: solder pasting

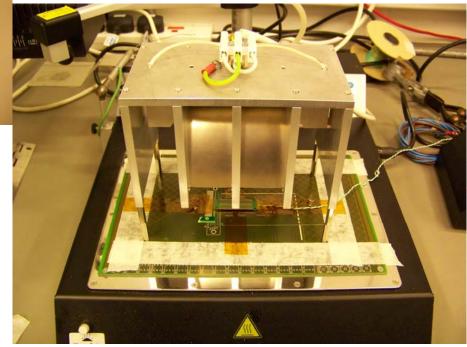




Linear Halogen Lamp

Elliptical Reflector

Re-flowing a PCB-Bridge

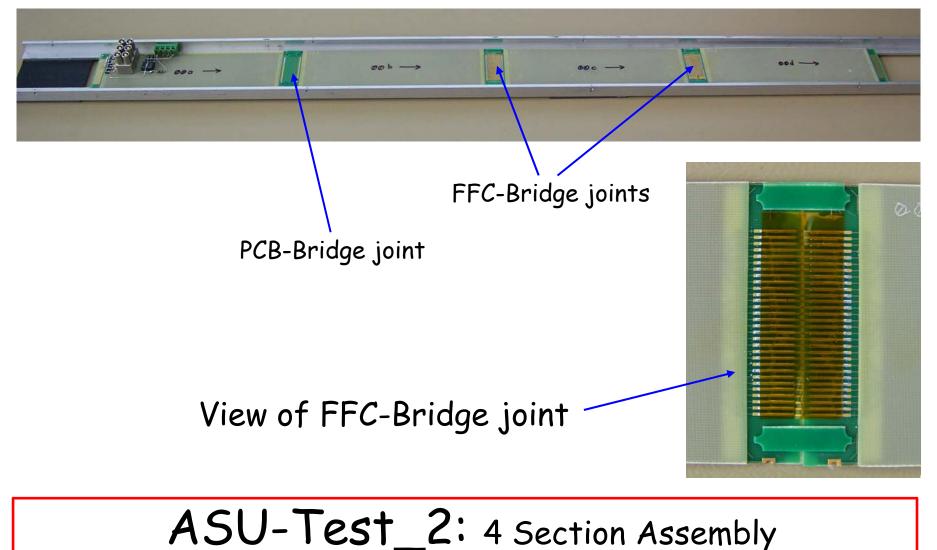


Imaging Halogen IR Source





4 Section ASU-Test Assembly







ASU-Test_2: 10 Section Assembly in Progress

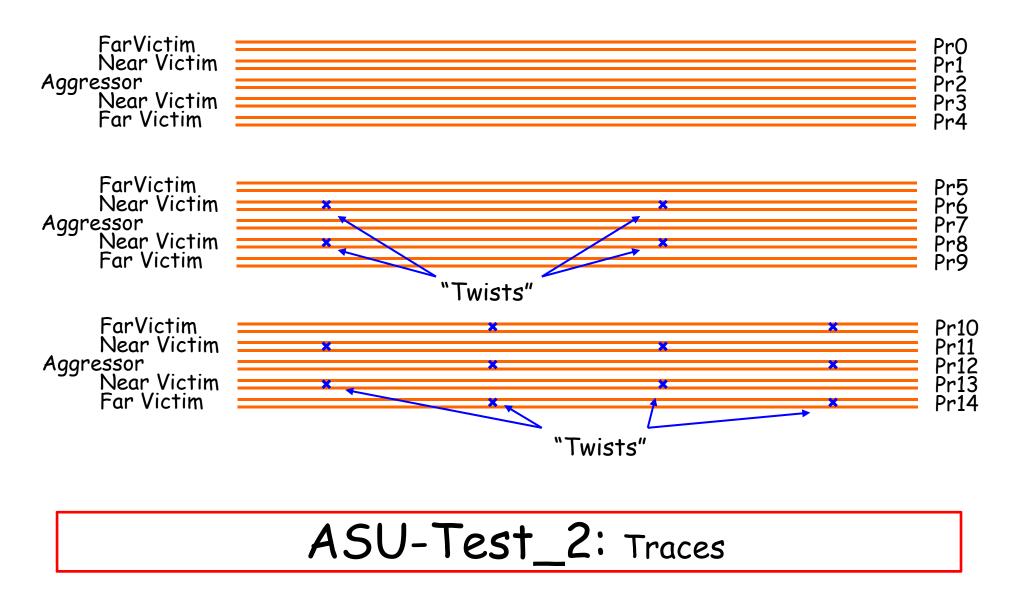


Using the 4 Section ASU-Test_2 Assembly



Crosstalk Setup

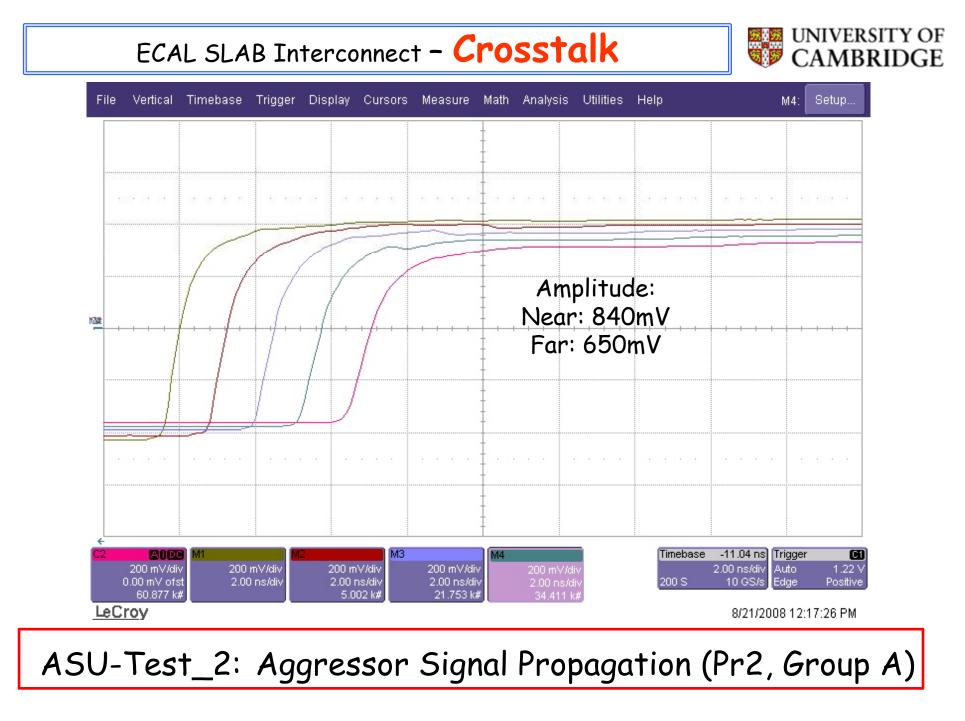




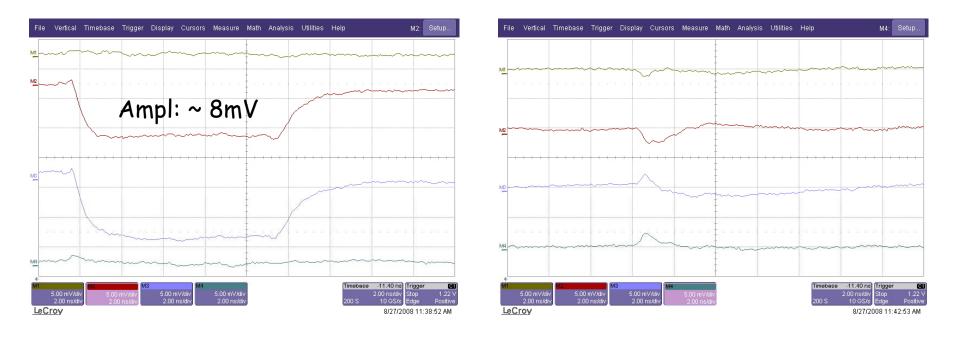


Group	Pair Separation/ (Track & Gap)			
Α	1			
В	1.5			
С	2			
D	3			

ASU-Test_2: Traces





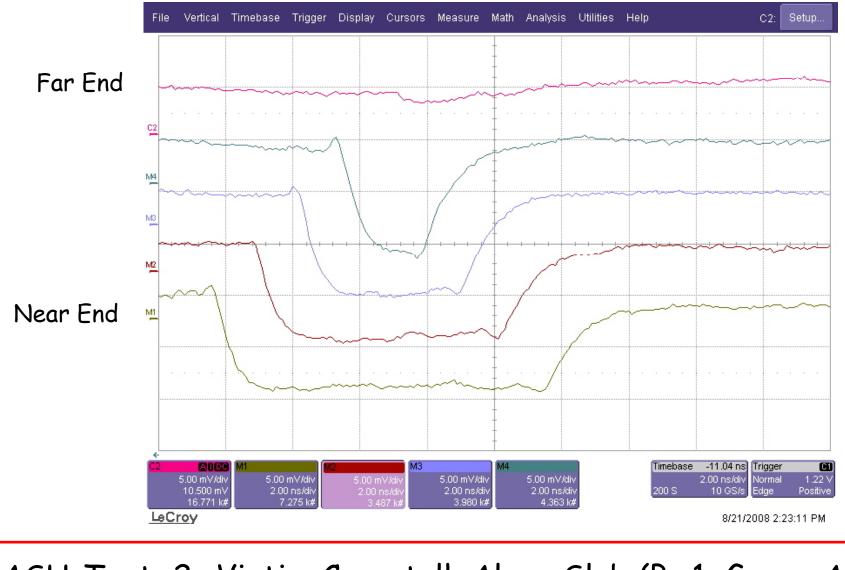


Driver End



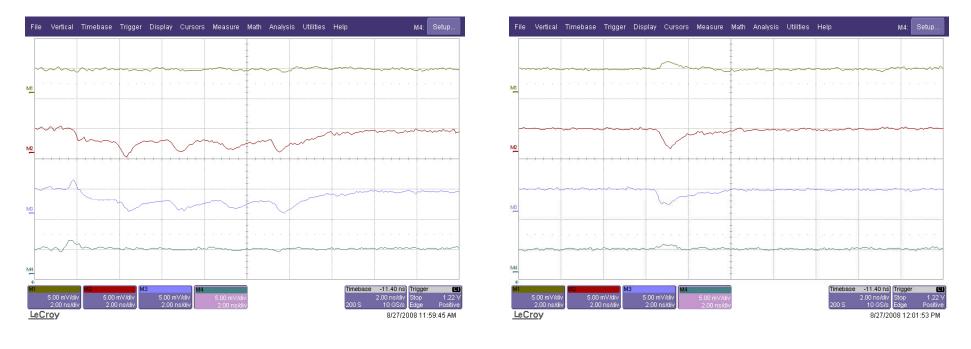
ASU-Test_2: Victim Crosstalk (Prs 0,1,3,4, Group A)





ASU-Test_2: Victim Crosstalk Along Slab (Pr 1, Group A)





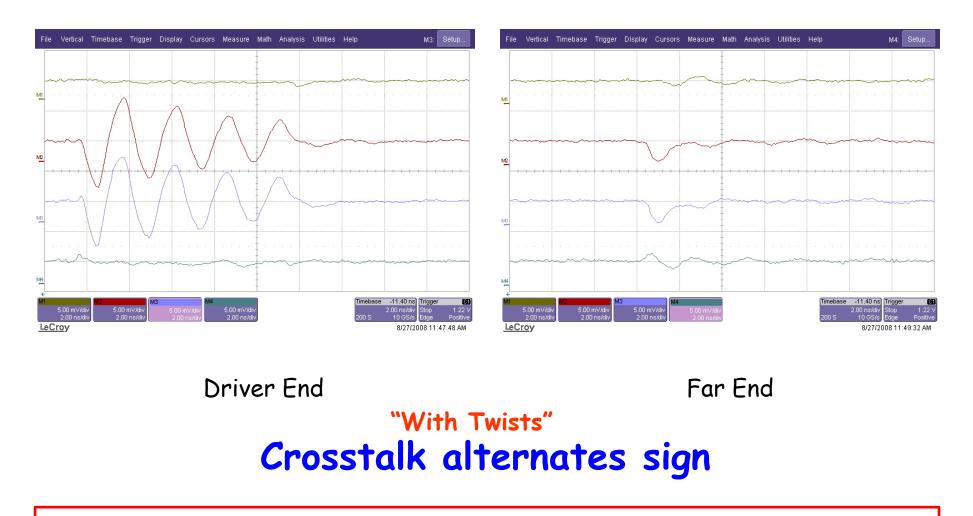
Driver End

Far End

Greater Pair Separation => Far Less Crosstalk

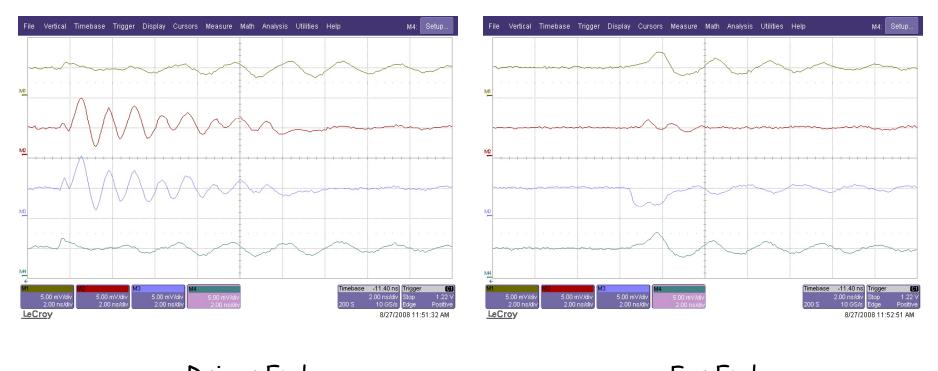
ASU-Test_2: Victim Crosstalk (Prs 0,1,3,4, Group C)





ASU-Test_2: Victim Crosstalk (Prs 5,6,8,9, Group A)





Driver End "With Extra Twists" Crosstalk alternates sign twice as fast

ASU-Test_2: Victim Crosstalk (Prs 10,11,13,14, Group A)





ASU-Test_2: Propagation with Added 10pFs at ASU Joints (Pr 2, Group C)



Conclusions: for the 750mm Assembly Signal degradation and crosstalk look relatively small, even with closely spaced pairs (~10mV) Pair separation of 2 x Track & Gap reduces crosstalk dramatically (confirming folk lore) "Twisting" pairs doesn't really help Periodic capacitive loads do have a perceptible effect (~100mV) - this will have to be watched

• What happens with 1700mm Slab? (10 ASU Slab being assembled) ECAL SLAB Interconnect - GlueTest



• Marc Anduze provided a number of 300um 90x90 glass plates (plus some of 500um)

- . We had 9 of them aluminised
- Manchester glued 2 of these to Gluetest PCBs
- . We have made initial resistance measurements
- Plan is to subject these to the IR soldering process, and to re-check the resistances

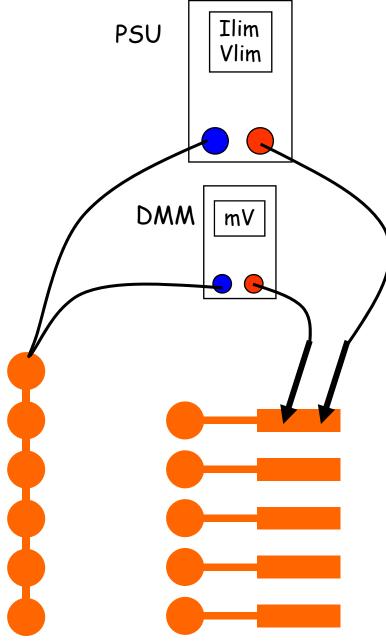
We find that glue joints are not simple!
 Ray Thompson of Manchester has written a very useful note on this

• We will use both leaded (183 deg) and Sn-Bi solder (150 deg)

 If these temperatures are a problem, it might push us to Laser Soldering

ECAL SLAB Interconnect - GlueTest Initial





GlueTest - PCB #1

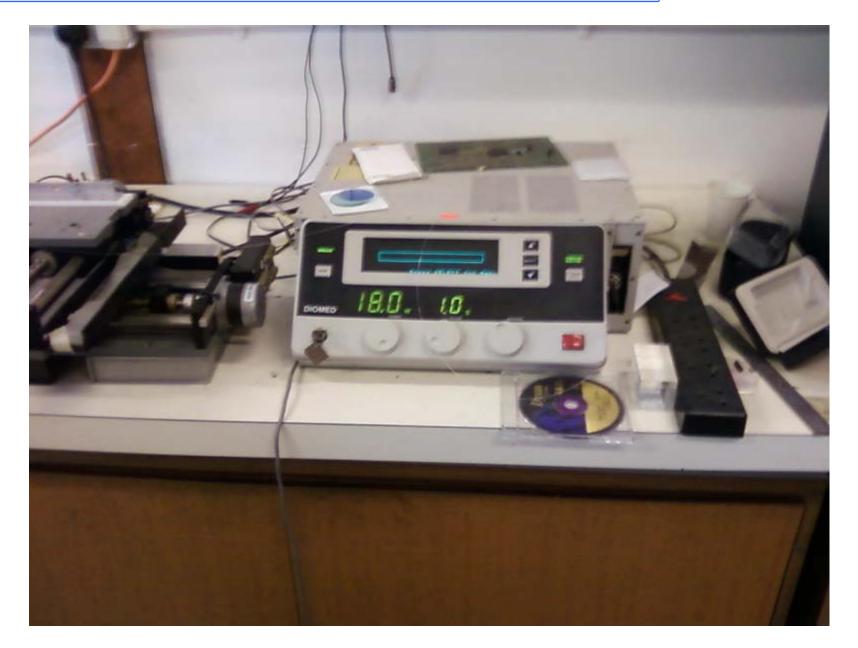
Connector #1									
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V Lim (V)	1	2	3	4	1	1			
Finger									
0	9.2	9.2	9.2	9.2	9.1	18			
1	9	9	9	9	9	18			
2	9.6	9.6	9.6	9.6	9.6	19			
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13	180	31	17	17	16	33			
14	1000	2000	33	29	29	58			
15	1000	2000	3000	22	22	44			
16	1000	31	16	16	16	32			
17	1000	2000	3000	18	19	38			
18	120	27	28	16	16	33			
19	1000	38	18	18	18	36			
20	1000	2000	3000	18	18	36			
21	1000	2000	3000	20	20	41			
22	1000	2000	3000	18	17	35			
23	1000	2000	15	15	15	30			
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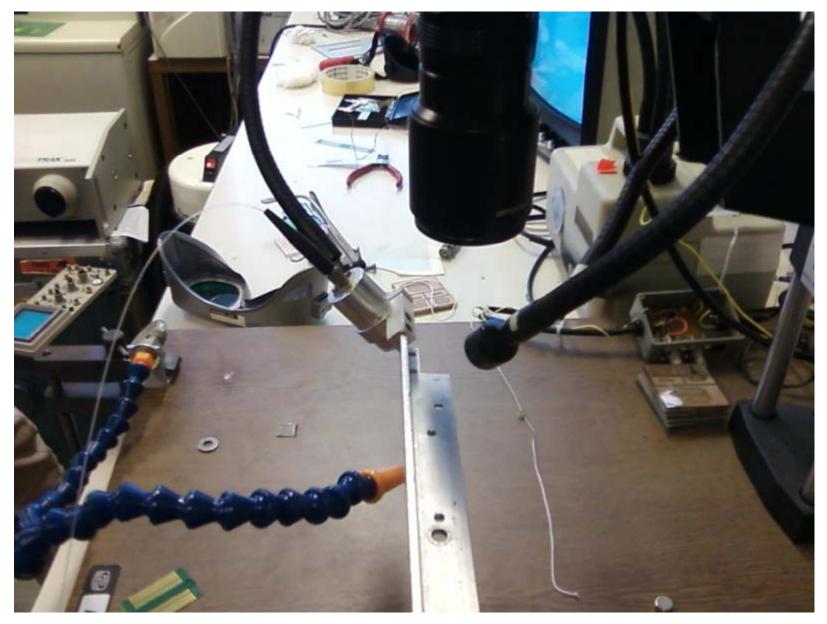
James Gilbert University of Hull Hull, UK



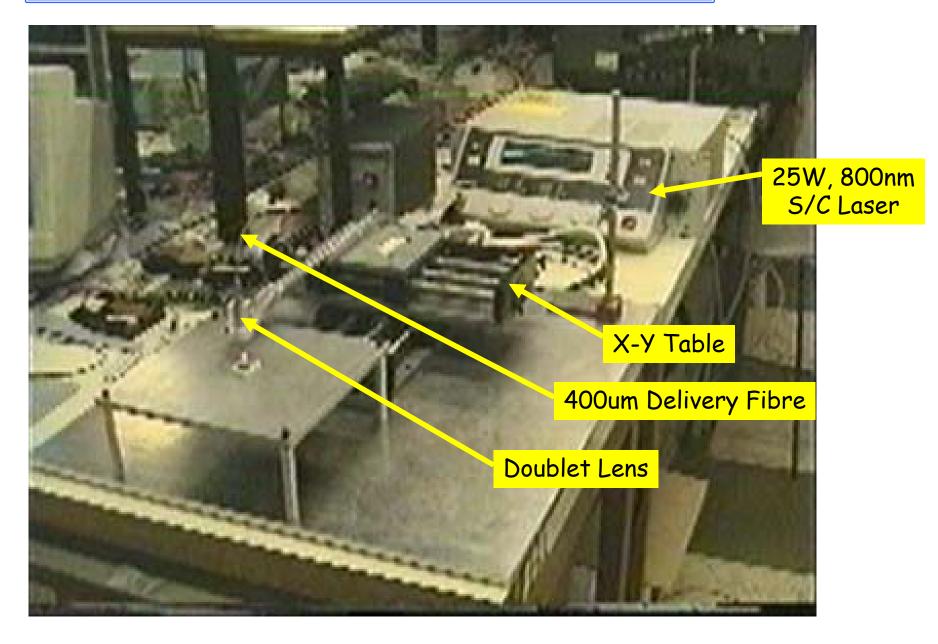


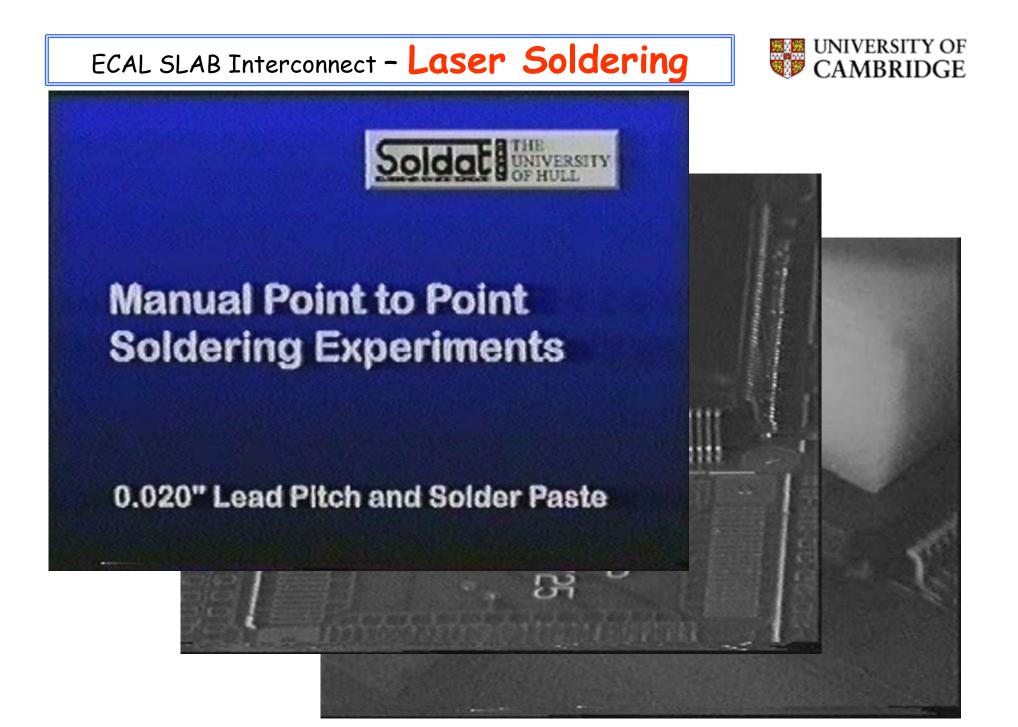
Maurice Goodrick & Bart Hommels , University of Cambridge













Laser Soldering: Conclusions

Promises low damage
~ 600 Euro/W: might need 10 - 25 W, so > 6000
Euro for laser
Possibly going to be a bit slow
Hull willing to do initial trials F.O.C.